



**Minutes of P-10 Committee on Integrated Passive Devices**

**Tuesday 07 October, 2003**

**Rivercenter Marriott**

**San Antonio, Texas**

**P-10 Committee's Scope:**

Will provide technical support and develops standards and specifications for electronic devices using mixed passive product technologies and diodes that perform a passive function, e.g., a) resistors and capacitors; b) resistors and diodes; c) resistors, capacitors, and inductors.

These devices may be discrete components that are “integrated” on a common substrate (hybrid) or in a carrier formed by a common manufacturing process (monolithic).

Activities also include the generation of terms and definitions, review of specifications, establishment of new specification criteria, and maintenance of existing criteria relating to these devices.

To accomplish these functions, the committee maintains liaison with and uses technical information from other standards development organizations (SDOs), government agencies, industry, various professional organizations, participating members, and guests.

**Attendees:**

<b>NAME</b>		<b>COMPANY</b>
Joe	Biernacki	SEI Electronics
Terry	Charles	Panasonic
Yumi	Chiong Aihara	KRFM America Inc.
Ted	Coler	Vishay
Dennis	Cross	DSCC
Michael	Griffith	KOA Speer
Kunifumi	Komiya	KRFM America Inc.
Patrick	Kyne	DSCC
Carl	Lindquist	San-O Industrial Corp.
Maher	Mahmud	IBM
Karun	Malhotra	Murata Electronics
Len	Metzger	Panasonic Ind’l Co
Ed	Mikoski	EIA/ECA
Randy	Pinkelman	Vishay
Chris	Reynolds	AVX
Dave	Ritchey	Yageo/Phycomp
Harvey	Waltersdorf	ECA

Michael	Whitney	IBM
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The meeting was called-to-order at 11:00 am by acting Chairman Michael Griffith

## 1.0 Introductions

## 2.0 Committee Organization and Procedures

### 2.1 Membership and Attendance

Attendance was taken, and it was determined that a quorum was present.

<b><u>Member Organizations Present</u></b>	<b><u>Present at this meeting</u></b>	<b><u>Present at previous meeting?</u></b>	<b><u>Present at meeting prior to previous?</u></b>
AVX	Yes	N	Y
DSCC	Yes	N	N
IBM	Yes	Y	Y
KOA Speer	Yes	Y	Y
KRFM America Inc.	Yes	N/A	N/A
Murata Electronics	Yes	Y	Y
Panasonic	Yes	Y	Y
San-O Industrial Corp.	Yes	Y	N
SEI Electronics	Yes	N	N
Vishay	Yes	Y	Y
Yageo/Phycomp	Yes	Y	Y

<b><u>Member Organizations Absent</u></b>	<b><u>Present at This Meeting?</u></b>	<b><u>Present at previous meeting?</u></b>	<b><u>Present at meeting prior to previous?</u></b>
AEM	No	Y	Y
Cornell Dubilier	No	Y	N
Maxwell Technologies	No	Y	N
Mini-Systems Inc.	No	Y	N
TDK Corporation	No	Y	N
Visteon	No	Y	N

\*Not counted in determination of quorum due to committee member inactivity

<b><u>Other Organizations Present</u></b>
EIA/ECA

## **2.2 Approval of Agenda**

The Committee unanimously accepted the Agenda as presented.

## **2.3 Approval of October, 2001 Meeting Minutes**

The Committee unanimously accepted the Minutes of the last meeting as written.

## **2.4 Correspondence**

No correspondence was received.

## **3.0 Old Business**

### **3.1 Status of PN-4944 (RC test performance spec) for EDEC approval**

Mr Piscitelli to resend n Electronic copy of the PN4944. A unanimous vote was taken to submit this out for review and comment upon EIA (Ed Mikoski) receiving this document. This specification will be submitted to ANSI upon the conclusion of the review and balloting process.

### **3.2 IPD Chip Scale Package Test (PN-4996):**

Mr Piscitelli to resend n Electronic copy of the PN4996. A unanimous vote was taken to submit this out for review and comment upon EIA (Ed Mikoski) receiving this document.

### **3.3 IPD Application Guideline status**

The application guideline has not been started. Mr Piscitelli to sent out a preliminary outline of the format for the application guideline to the working group (Steve Olster & Randy Pinkleman)

### **3.4 Review additional IPD Circuit Registration Requests**

No new IPD registrations have been received.

### **3.5 Other**

It was brought to this committees attention that NEDA (National Electronics Distribution Association) is creating IPD specifications for the disty facilities, in regards to standard packaging and labeling. Currently NEDA has a specification (JEP130) which is covered by JEDEC. JEP130 currently is vague in whether it refers to Active or Passives, because of the vague wording the P10 group should have had input into this document. Michael Griffith (KOA) has agreed to go the next NEDA meeting (October 21~22, 2003) be the liason for ECA & P10 group. A summary of the NEDA meeting will be presented to the April 2004 ECA meetings.

As an additional note when NEDA moves forward with a passives IPD document the EIA representative will insure that the NEDA document has the IPD registration document placed within the NEDA specification. Upon completion of this specification from NEDA it will be sent to P-10 for review and approval. A F/up of this specification from NEDA is planned at the April 2004 meeting.

## **4.0 New Business**

**4.1 Status of Supplying IPD outlines to P-4.**

Brian Piscitelli to contact Michael Griffith to insure outlines are supplied to the P-4 committee in April 2004.

**5.0 Next Meeting**

**5.1** The next meeting will be at the ECA Spring Engineering Summit to be held in April 2004 in Tampa Florida.

**6.0 Adjournment**

The meeting was adjourned at 11:40 AM.

**This meeting was conducted in accordance with the EIA Legal Guidelines and the Manual of Organization and Procedures.**

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Michael Griffith  
Acting Chairman

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Edward F. Mikoski, Jr.  
Acting Secretary